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## **Fraunhofer EMFT Signs Agreement to Implement ZiBond and DBI Technologies in MEMS Applications**

SAN JOSE, Calif.--(BUSINESS WIRE)-- Invensas Corporation, a wholly owned subsidiary of Tessera Technologies, Inc., (Nasdaq:TSRA) announced today that Fraunhofer EMFT has signed a new license agreement to incorporate ZiBond® and Direct Bond Interconnect (DBI®) technologies into their portfolio of foundry services. This agreement expands Fraunhofer EMFT's world-class MEMS manufacturing capabilities with the most advanced 3D integration technologies available.

"ZiBond and DBI technologies are truly enabling bonding and 3D integration technologies for next generation electronic products," said Dr. Peter Ramm, department head, Heterogeneous System Integration at Fraunhofer EMFT. "We look forward to working with Invensas and our global customer base to demonstrate and further optimize these technologies for MEMS applications on our production equipment," added Prof. Dr. Christoph Kutter, director of Fraunhofer EMFT.

ZiBond and DBI technologies are cost-effective, versatile 2.5D and 3D semiconductor integration solutions that enable leading edge functionality and accelerate time to market for MEMS and multiple other semiconductor products. ZiBond and DBI bonding can be performed at room temperature without requiring bond pressure. Bonding is typically completed in less than a minute for an entire wafer, substantially reducing manufacturing cost.

"Scaling based on Moore's Law is becoming increasingly challenging and this is driving demand for our ZiBond and DBI bonding and 3D interconnect technologies, which have been proven in high volume production environments," said Craig Mitchell, president of Invensas Corporation. "We are pleased that Fraunhofer EMFT, a highly respected MEMS research and 3D heterogeneous integration, development and pilot manufacturing center of excellence, has chosen our ZiBond and DBI technologies to help their customers accelerate the development and commercialization of their next generation MEMS products."

For more information on ZiBond, DBI and other Invensas solutions, please visit [www.invensas.com](http://www.invensas.com) or [www.tessera.com](http://www.tessera.com).

### **About Tessera Technologies, Inc.**

Tessera Technologies, Inc., including its Invensas and FotoNation subsidiaries, licenses technologies and intellectual property to customers for use in areas such as mobile computing and communications, memory and data storage, and 3D-IC technologies, among others. Our technologies include semiconductor packaging and interconnect solutions, and computational imaging and computer vision products and solutions for mobile and other vision systems. For more information call +1.408.321.6000 or visit [www.tessera.com](http://www.tessera.com) or [www.invensas.com](http://www.invensas.com).

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### **About Fraunhofer EMFT**

Fraunhofer EMFT conducts cutting-edge applied research into sensors and actuators for people and the environment. The core competences of the research departments in Munich with hundred employees include the fields of silicon technologies, devices and 3D integration, as well as foil technologies, micropumps, sensor materials and the capability of system integration. The real strength of Fraunhofer EMFT lies in the interaction between these areas: after all, innovations often emerge where technologies reach their limits and begin to cross-fertilize.

### **Safe Harbor Statement**

This press release contains forward-looking statements, which are made pursuant to the safe harbor provisions of the Private Securities Litigation Reform Act of 1995. Forward-looking statements involve risks and uncertainties that could cause actual results to differ significantly from those projected, particularly with respect to the agreement with Fraunhofer and the features, benefits and characteristics of ZiBond and DBI. Material factors that may cause results to differ from the statements made include the plans or operations relating to the businesses of Tessera Technologies, Inc. (the "Company"); market or industry conditions; changes in patent laws, regulation or enforcement, or other factors that might affect the Company's ability to protect or realize the value of its intellectual property; the expiration of license agreements and the cessation of related royalty income; the failure, inability or refusal of licensees to pay royalties; initiation, delays, setbacks or

losses relating to the Company's intellectual property or intellectual property litigations, or invalidation or limitation of key patents; fluctuations in operating results due to the timing of new license agreements and royalties, or due to legal costs; the risk of a decline in demand for semiconductors and products utilizing FotoNation technologies; failure by the industry to use technologies covered by the Company's patents; the expiration of the Company's patents; the Company's ability to successfully complete and integrate acquisitions of businesses; the risk of loss of, or decreases in production orders from, customers of acquired businesses; financial and regulatory risks associated with the international nature of the Company's businesses; failure of the Company's products to achieve technological feasibility or profitability; failure to successfully commercialize the Company's products; changes in demand for the products of the Company's customers; limited opportunities to license technologies due to high concentration in the markets for semiconductors and related products and smartphone imaging; and the impact of competing technologies on the demand for the Company's technologies. You are cautioned not to place undue reliance on the forward-looking statements, which speak only as of the date of this release. The Company's filings with the Securities and Exchange Commission, including its Annual Report on Form 10-K for the year ended Dec. 31, 2015 and its Quarterly Report on Form 10-Q for the quarter ended June 30, 2016, include more information about factors that could affect the Company's financial results. The Company assumes no obligation to update information contained in this press release. Although this release may remain available on the Company's website or elsewhere, its continued availability does not indicate that the Company is reaffirming or confirming any of the information contained herein.

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